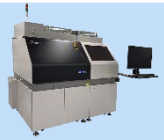
3D Metrology

Purpose	True 3D Measurement Solutions for various process points such as Wafer Bumping, Post Dicing, Assembly & Post Test
Technology	1. **OTF Triangulation 3D** – Designed for high-volume, high-speed 3D Metrology solutions for ≥ 20µm bump height 2. **True Mold Thickness** – Patented Solution to measure 360-degree 3D topology measurement at production speed for packages used in portable mobility devices 3. **3D LPS** – Designed for high-volume, high-speed 3D metrology solutions for ≥ 5µm bump height

STI Products	OTF Triangulation	3D LPS	True Mold Thickness
 **iFocus – Wafer 2D & 3D Scan**	✓	✓	
 **Hexa – Tray 2D & 3D Scan**	✓		✓
 **tScan – 2D & 3D High Speed Scan-Pack**	✓		✓